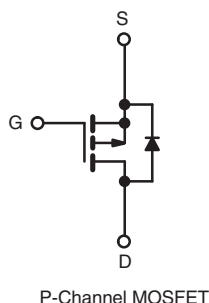
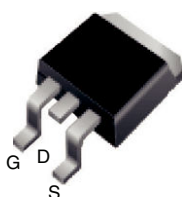


Power MOSFET

PRODUCT SUMMARY

V_{DS} (V)	- 200	
$R_{DS(on)}$ (Ω)	$V_{GS} = -10$ V	3
Q_g (Max.) (nC)	11	
Q_{gs} (nC)	7	
Q_{gd} (nC)	4	
Configuration	Single	

D²PAK (TO-263)


FEATURES

- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- P-Channel
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

Note

* Lead (Pb)-containing terminations are not RoHS-compliant. Exemptions may apply.

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D²PAK (TO-263) is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²PAK (TO-263) is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2 W in a typical surface mount application.



RoHS*
COMPLIANT
HALOGEN
FREE
Available

ORDERING INFORMATION

Package	D ² PAK (TO-263)
Lead (Pb)-free and Halogen-free	SiHF9610S-GE3
	SiHF9610STRR-GE3
	SiHF9610STRL-GE3
Lead (Pb)-free	IRF9610SPbF
	SiHF9610S-E3
	IRF9610STRRPbF
	IRF9610STRLPbF

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	- 200	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	V_{GS} at - 10 V	$T_C = 25^\circ\text{C}$	A
		$T_C = 100^\circ\text{C}$	
Pulsed Drain Current ^a	I_{DM}	- 7	W/ $^\circ\text{C}$
Linear Derating Factor		0.16	
Linear Derating Factor (PCB Mount) ^d		0.025	
Maximum Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	W
Maximum Power Dissipation (PCB Mount) ^d		$T_A = 25^\circ\text{C}$	
Peak Diode Recovery dV/dt ^b	dV/dt	- 5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s	300 $^\circ\text{C}$	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 5).
- $I_{SD} \leq -1.8$ A, $dI/dt \leq 70$ A/ μs , $V_{DD} \leq V_{DS}$, $T_J \leq 150^\circ\text{C}$.
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

**THERMAL RESISTANCE RATINGS**

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount) ^a	R_{thJA}	-	40	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	6.4	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS ($T_J = 25\text{ °C}$, unless otherwise noted)

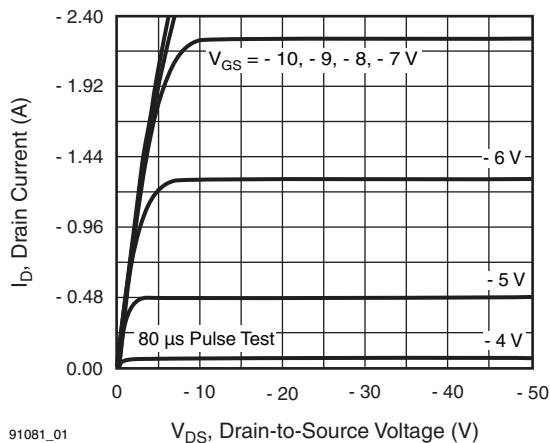
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = - 250 μA		- 200	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = - 1 mA		-	- 0.23	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 2	-	- 4	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V		-	-	- 100	μA
		V _{DS} = - 160 V, V _{GS} = 0 V, T _J = 125 °C		-	-	- 500	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 0.90 A ^b	-	-	3	Ω
Forward Transconductance	g _{fs}	V _{DS} = - 50 V, I _D = - 0.90 A ^b		0.90	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz, see fig. 10		-	170	-	pF
Output Capacitance	C _{oss}			-	50	-	
Reverse Transfer Capacitance	C _{rss}			-	15	-	
Total Gate Charge	Q _g	V _{GS} = - 10 V	I _D = - 3.5 A, V _{DS} = - 160 V, see fig. 11 and 18 ^b	-	-	11	nC
Gate-Source Charge	Q _{gs}			-	-	7	
Gate-Drain Charge	Q _{gd}			-	-	4	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 100 V, I _D = - 0.90 A, R _G = 50 Ω, R _D = 110 Ω, see fig. 17 ^b		-	8	-	ns
Rise Time	t _r			-	15	-	
Turn-Off Delay Time	t _{d(off)}			-	1	-	
Fall Time	t _f			-	8	-	
Internal Drain Inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L _S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 1.8	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	- 7	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = - 1.8 A, V _{GS} = 0 V ^b		-	-	- 5.8	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = - 1.8 A, dI/dt = 100 A/μs ^b		-	240	360	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	1.7	2.6	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 5).
b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

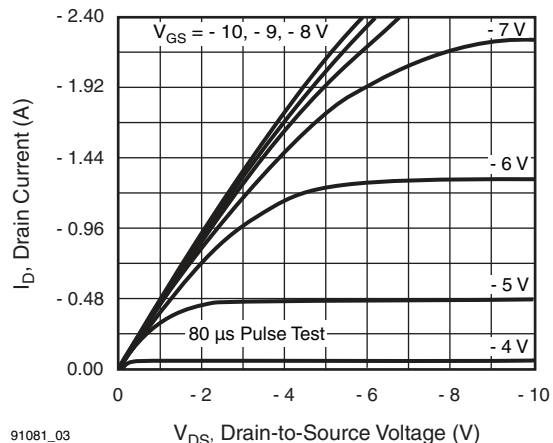


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



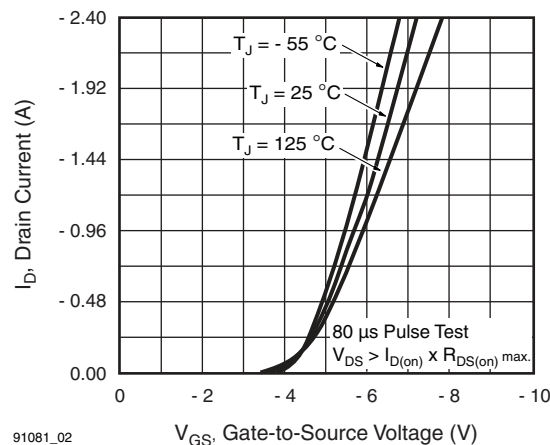
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Fig. 1 - Typical Output Characteristics



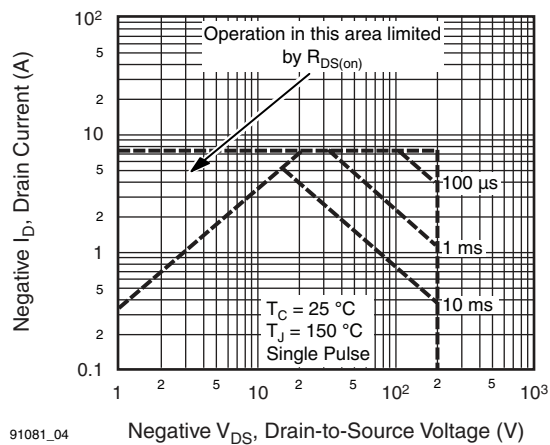
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Fig. 3 - Typical Saturation Characteristics



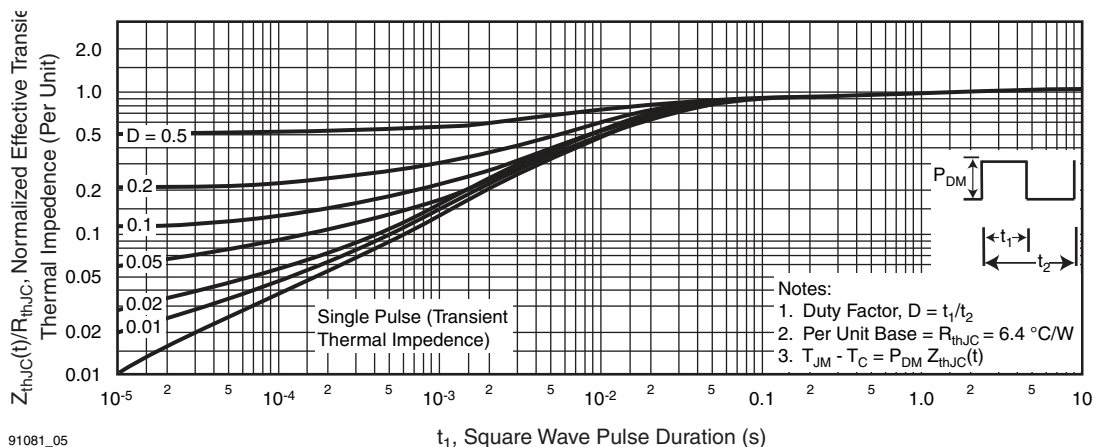
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Fig. 2 - Typical Transfer Characteristics



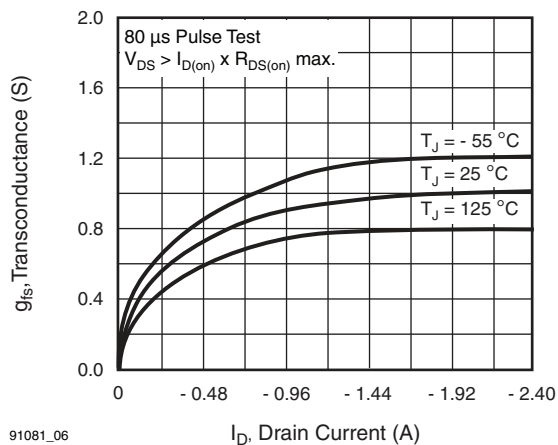
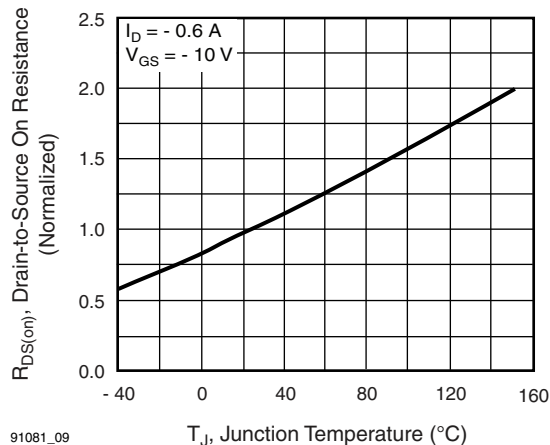
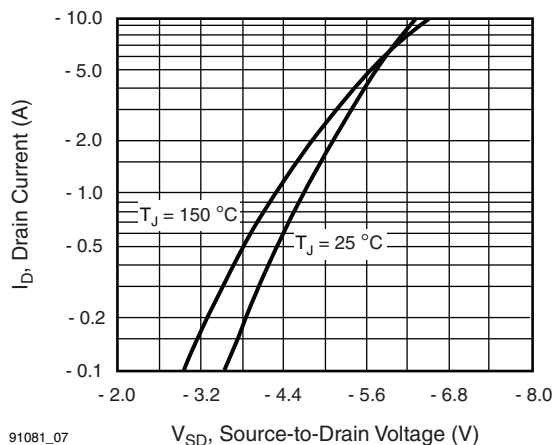
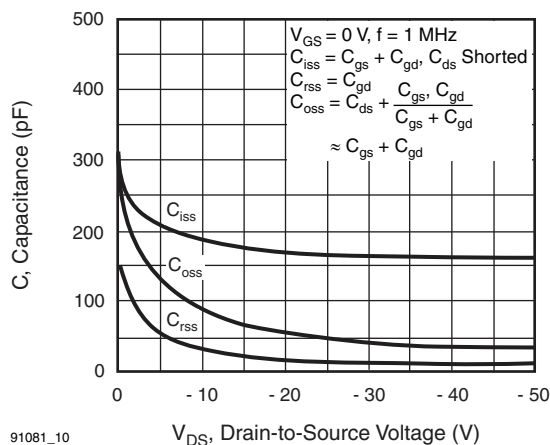
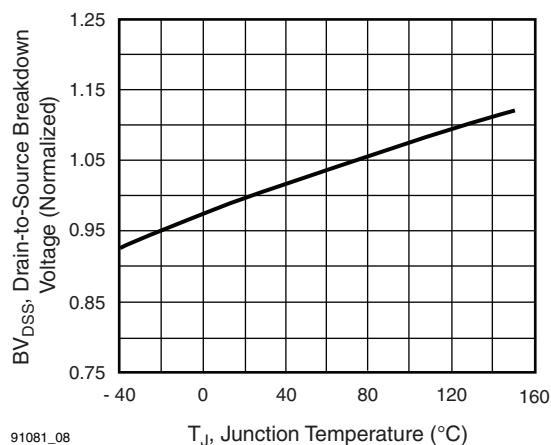
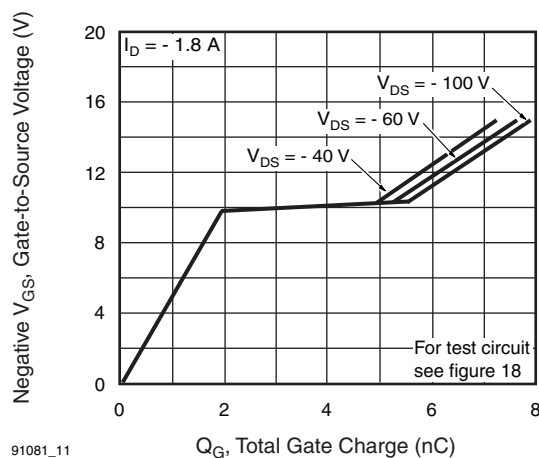
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Fig. 4 - Maximum Safe Operating Area



91081_05

Fig. 5 - Maximum Effective Transient Thermal Impedance, Junction-to-Case vs. Pulse Duration


Fig. 6 - Typical Transconductance vs. Drain Current

Fig. 9 - Normalized On-Resistance vs. Temperature

Fig. 7 - Typical Source-Drain Diode Forward Voltage

Fig. 10 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 8 - Breakdown Voltage vs. Temperature

Fig. 11 - Typical Gate Charge vs. Gate-to-Source Voltage

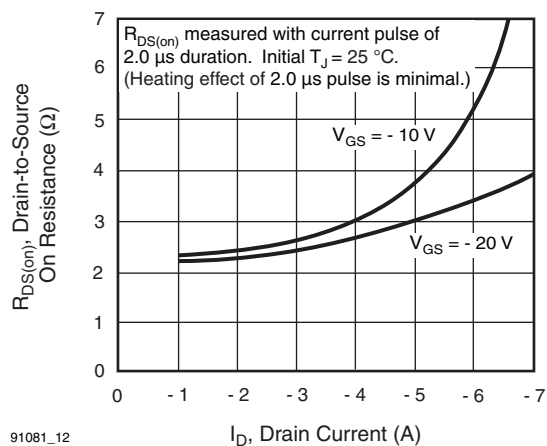


Fig. 12 - Typical On-Resistance vs. Drain Current

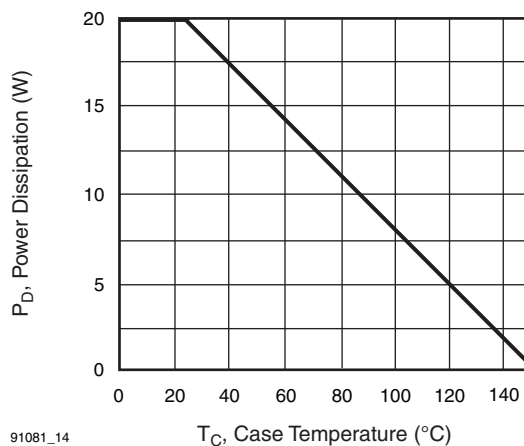


Fig. 14 - Power vs. Temperature Derating Curve

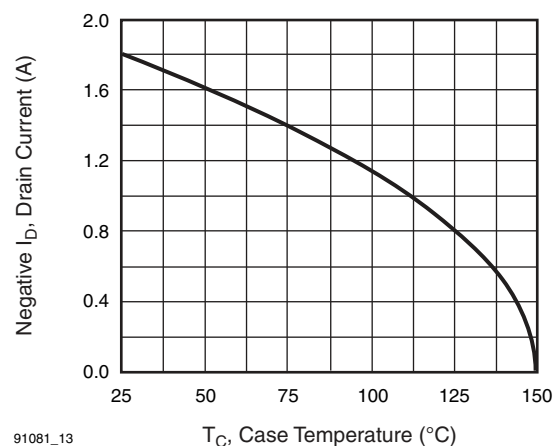


Fig. 13 - Maximum Drain Current vs. Case Temperature

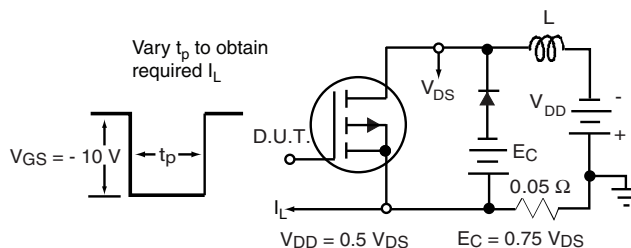


Fig. 15 - Clamped Inductive Test Circuit

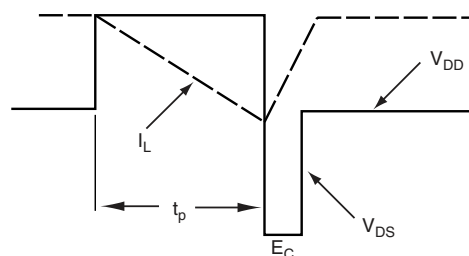
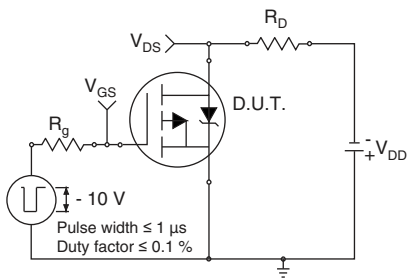
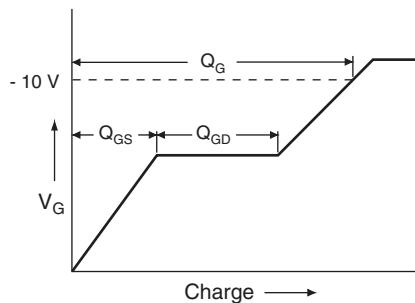
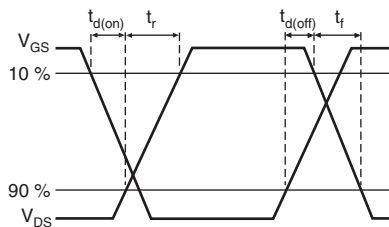
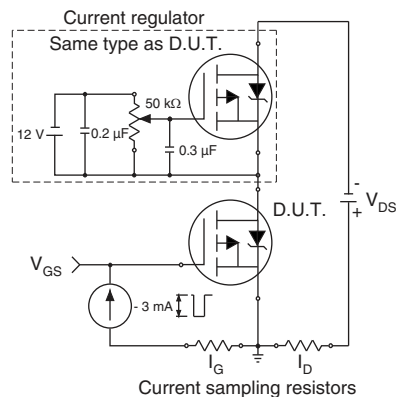


Fig. 16 - Clamped Inductive Waveforms


Fig. 17a - Switching Time Test Circuit

Fig. 18a - Basic Gate Charge Waveform

Fig. 17b - Switching Time Waveforms

Fig. 18b - Gate Charge Test Circuit

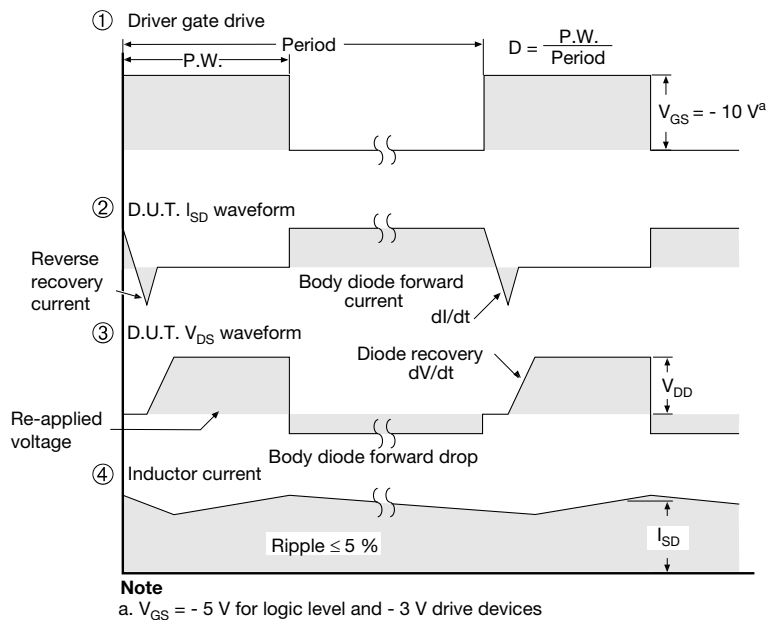
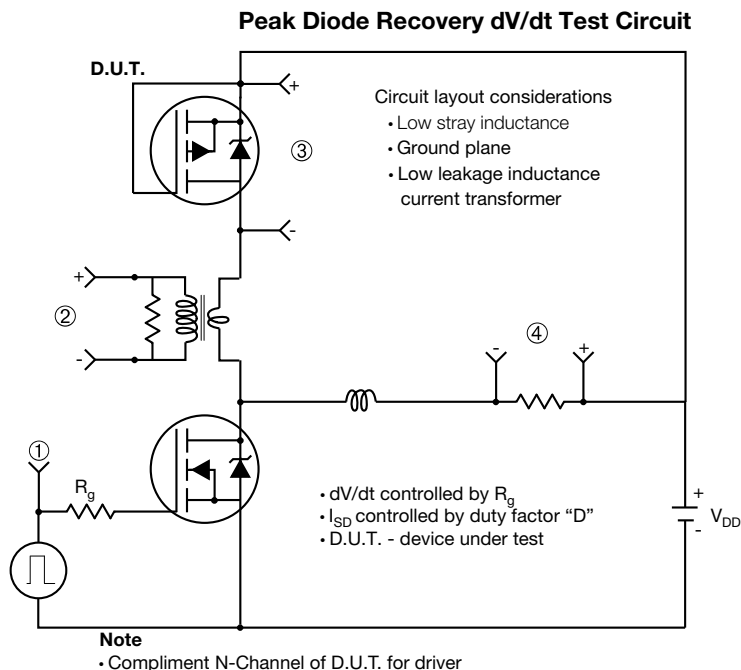
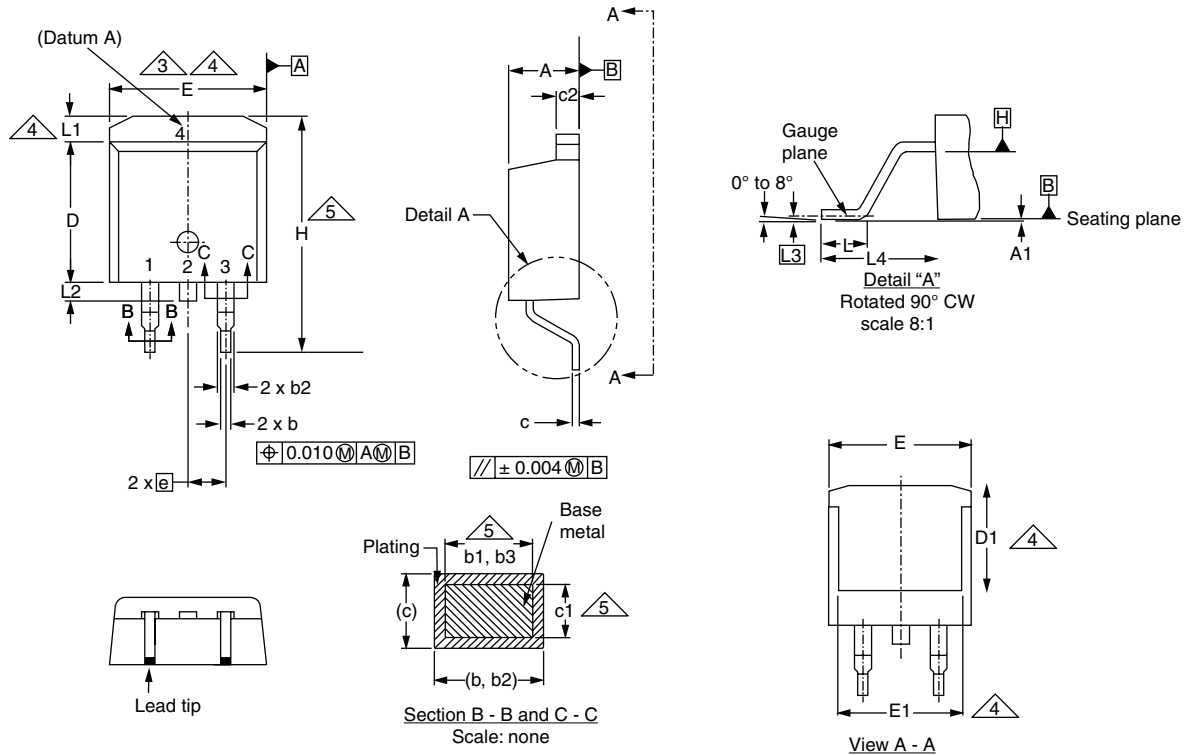


Fig. 19 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91081.

TO-263AB (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.06	4.83	0.160	0.190
A1	0.00	0.25	0.000	0.010
b	0.51	0.99	0.020	0.039
b1	0.51	0.89	0.020	0.035
b2	1.14	1.78	0.045	0.070
b3	1.14	1.73	0.045	0.068
c	0.38	0.74	0.015	0.029
c1	0.38	0.58	0.015	0.023
c2	1.14	1.65	0.045	0.065
D	8.38	9.65	0.330	0.380

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	6.86	-	0.270	-
E	9.65	10.67	0.380	0.420
E1	6.22	-	0.245	-
e	2.54 BSC		0.100 BSC	
H	14.61	15.88	0.575	0.625
L	1.78	2.79	0.070	0.110
L1	-	1.65	-	0.066
L2	-	1.78	-	0.070
L3	0.25 BSC		0.010 BSC	
L4	4.78	5.28	0.188	0.208

ECN: S-82110-Rev. A, 15-Sep-08
DWG: 5970

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.

RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads
Dimensions in Inches/(mm)

[Return to Index](#)



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